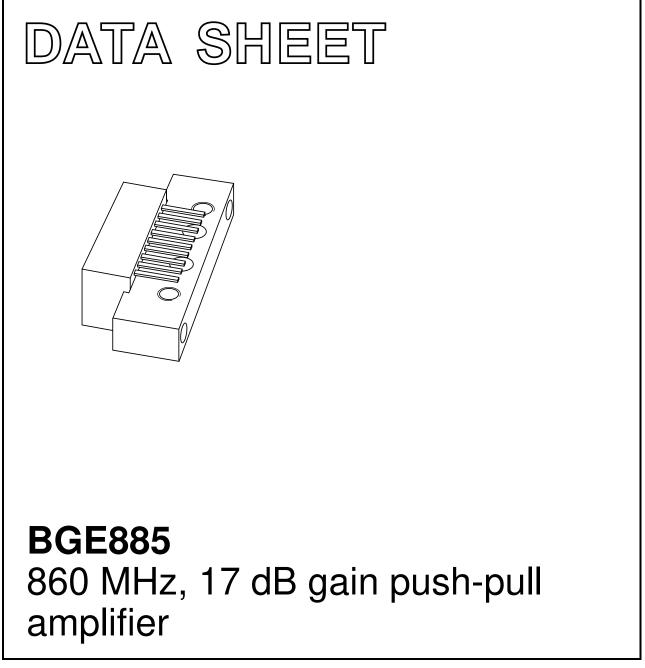
# DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1999 Mar 30 2001 Oct 31



### **BGE885**

### FEATURES

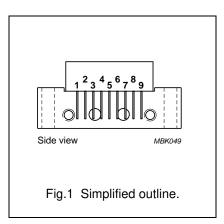
- · Excellent linearity
- Extremely low noise
- Rugged construction
- TiPtAu metallized crystals ensure optimal reliability.

### DESCRIPTION

Hybrid amplifier module for use in CATV systems operating over a frequency range of 40 to 860 MHz with a voltage supply of 24 V (DC).

### **PINNING - SOT115D**

PIN DESCRIPTION 1 input; note 1 2 common 3 common 12 V, 60 mA supply terminal 4 5 common 6 common 7 common 8 +V<sub>B</sub> 9 output; note 1



### Note

1. Pins 1 and 9 carry DC voltages.

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G <sub>p</sub>	power gain	f = 50 MHz	16.5	17.5	dB
I <sub>tot</sub>	total current consumption (DC)	V <sub>B</sub> = 24 V	-	240	mA

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>B</sub>	DC supply voltage	-	28	V
Vi	RF input voltage	-	65	dBmV
T <sub>stg</sub>	storage temperature	-40	+100	°C
T <sub>mb</sub>	operating mounting base temperature	-20	+100	°C

### **BGE885**

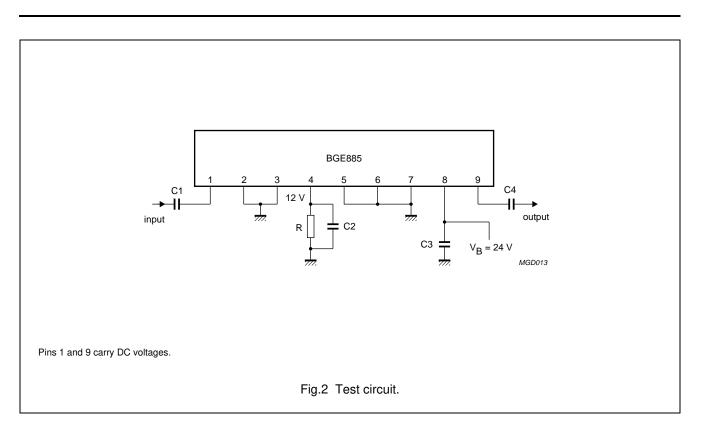
### CHARACTERISTICS

Bandwidth 40 to 860 MHz; V\_B = 24 V; T\_{mb} = 30 °C; Z\_S = Z\_L = 75  $\Omega$ 

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G <sub>p</sub>	power gain	f = 50 MHz	16.5	17.5	dB
SL	slope cable equivalent	f = 40 to 860 MHz	0.2	1.2	dB
FL	flatness of frequency response	f = 40 to 860 MHz	-	±0.5	dB
s <sub>11</sub>	input return losses	f = 40 to 450 MHz	14	_	dB
		f = 450 to 860 MHz	10	_	dB
\$ <sub>22</sub>	output return losses	f = 40 to 450 MHz	14	_	dB
		f = 450 to 860 MHz	10	_	dB
d <sub>2</sub>	second order distortion	note 1	-	-53	dB
Vo	output voltage	$d_{im} = -60 \text{ dB}; \text{ note } 2$	59	_	dBmV
F	noise figure	f = 350 MHz	-	7.5	dB
		f = 860 MHz	-	8	dB
I <sub>tot</sub>	total current consumption (DC)	note 3	-	240	mA

### Notes

- 1.  $f_p = 349.25 \text{ MHz}; V_p = 59 \text{ dBmV};$  $f_q = 403.25 \text{ MHz}; V_q = 59 \text{ dBmV};$ measured at  $f_p + f_q = 752.5 \text{ MHz}.$
- 2. Measured according to DIN45004B:  $f_p = 851.25 \text{ MHz}; V_p = V_o = 59 \text{ dBmV};$   $f_q = 858.25 \text{ MHz}; V_q = V_o -6 \text{ dB};$   $f_r = 860.25 \text{ MHz}; V_r = V_o -6 \text{ dB};$ measured at  $f_p + f_q - f_r = 849.25 \text{ MHz}.$
- 3. The module normally operates at  $V_B = 24$  V, but is able to withstand supply transients up to 30 V.



### List of components (see Fig.2)

COMPONENT	DESCRIPTION	VALUE
C1, C3, C4	ceramic multilayer capacitor	1 nF
C2	ceramic multilayer capacitor	1 nF (max.)
R	resistor	200 Ω,1 W

## BGE885

2001 Oct 31

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes;

#### 2 x 6-32 UNC and 2 extra horizontal mounting holes; 9 gold-plated in-line leads SOT115D D Е Ζ A<sub>2</sub> 2 3 4 5 6 7 8 9 L s w е b () w (M) с – - **–** y M B $q_2$ -> d e<sub>1</sub> -- Q --U<sub>2</sub> q1 В = y M B р U<sub>1</sub> q 0 5 10 mm 0 scale DIMENSIONS (mm are the original dimensions) A2 D Q z Α d Е L UNIT b с е e<sub>1</sub> F р q q1 q2 s U1 U2 w w х у max. max. min. max. max max. max. max 4.15 3.85 0.51 44.75 44.25 8.2 7.8 6-32 UNC 0.25 27.2 2.54 13.75 2.54 5.08 12.7 38.1 25.4 10.2 4.2 0.25 mm 20.8 9.5 8.8 2.4 0.7 0.1 3.8 0.38 REFERENCES EUROPEAN OUTLINE ISSUE DATE PROJECTION VERSION IEC JEDEC JEITA -04-02-04 $\bigcirc \bigcirc$ SOT115D 10-06-18

# 860 MHz, 17 dB gain push-pull amplifier

# PACKAGE OUTLINE

BGE885

### **BGE885**

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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#### **Contact information**

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